

## AMENDMENT TO THE CLAIMS:

The following claim set replaces all prior versions, and listings, of claims in the application:

1. (currently amended) A method for producing a resin composition pellet from a comprised of a resin (A) and a fibrous filler (B), the method comprising: ~~in~~ which a weight average fiber length (L) of a fibrous filler (B) is 180 to 360  $\mu$ m, comprising
  - (a) supplying to an extruder an amount of 55 to 80% to 55% by weight of feed pellets comprised of the resin (A) and 20 to 45% by weight of the fibrous filler (B), the fibrous filler (B) having with a weight average fiber length (L) of 1 mm or more based on the (herein, a total weight of the resin (A) and the fibrous filler (B), is 100% by weight) to an extruder, wherein the step of supplying the resin (A) and the fibrous filler (B) to the extruder includes:
    - (i) supplying one [[a]] part containing [[of]] an amount (x) of the feed pellets comprised of the resin (A) is supplied through a main feed port of the extruder; and
    - (ii) supplying the fibrous filler (B) and a remaining part amount (1-x) of the feed pellets comprised of the resin (A) containing an amount (1-x) are supplied through a side-feed port provided downstream of the main feed port backward in an extrusion direction of the extruder from the main feed port so that a weight ratio of x/(1-x) is becomes 50/50 to 10/90% by weight
  - (b) melt-blending the one and another parts of the resin (A) with the fibrous filler (B) within the extruder to achieve a weight average fiber length (L) of the fibrous filler (B) of 180 to 360  $\mu$ m based on the total weight of the resin (A) and the fibrous filler (B), and thereafter
  - (c) forming a pellet of the melt-blended resin (A) and the fibrous filler (B).
2. (currently amended) A method for producing a resin composition pellet according to claim 1, wherein 5 to 40% by weight a proportion of the fibrous

filler (B) in the pellet has ~~[[with]]~~ a fiber length exceeding 300  $\mu\text{m}$  ~~in the resin composition pellet is 5 to 40% by weight.~~

3. (currently amended) A method for producing a ~~resin composition~~ pellet according to claim 1, comprising melt-blending the resin (A) and the fibrous filler (B) in a ~~wherein the resin composition pellet is obtained by one-pass treatment~~ ~~[[with]]~~ through the extruder.
4. (currently amended) A method for producing a ~~resin composition~~ pellet according to claim 1, wherein the resin (A) comprises a liquid crystalline polymer.
5. (currently amended) A method for producing a ~~resin composition~~ pellet according to claim 1, wherein the fibrous filler (B) comprises at least one filler selected from the group consisting of ~~[[a]]~~ glass fibers ~~fiber~~ and ~~[[a]]~~ carbon fiber ~~fibers~~.
6. (canceled)
7. (currently amended) A method for producing a ~~resin composition~~ pellet according to claim 1, wherein the extruder comprises a twin-screw extruder having a plasticizing zone, a kneading zone, and a ratio (L/D) between ~~[[a]]~~ screw length (L) and ~~[[a]]~~ screw diameter (D) of (L/D) is 20 or more, ~~a screw has a plasticizing zone and a kneading zone, and wherein~~ the side-feed port is positioned ~~on a downstream side of the plasticizing zone.~~
8. (currently amended) A method for producing a resin composition pellet according to claim 1, wherein ~~the~~ a melt viscosity of the resin composition pellet ~~[[is]]~~ has a melt viscosity of 10 to 55 Pa·s.
9. (currently amended) ~~A method for producing a~~ An injection-molded product made by producing a resin composition pellet according to claim 1, and thereafter injection molding the resin composition pellet to produce an

~~injection-molded product therefrom, wherein [[a]] the injection-molded product obtained by molding a resin composition pellet by injection~~ has a flexural modulus of 15,000 MPa or more, a flatness before solder reflow treatment of 0.09 mm or less, and a difference in flatness before and after heating corresponding to the solder reflow treatment at a peak temperature of 230 to 280°C of 0.02 mm or less.

10. (new) An injection-molded product according to claim 9 in the form of a planar socket for a semiconductor device, wherein the planar socket has a height of 5.0 mm or less and includes a lattice area provided with a number of pin holes, the lattice area having a thickness of 0.5 mm or less and a pitch interval of 2.0 mm or less.